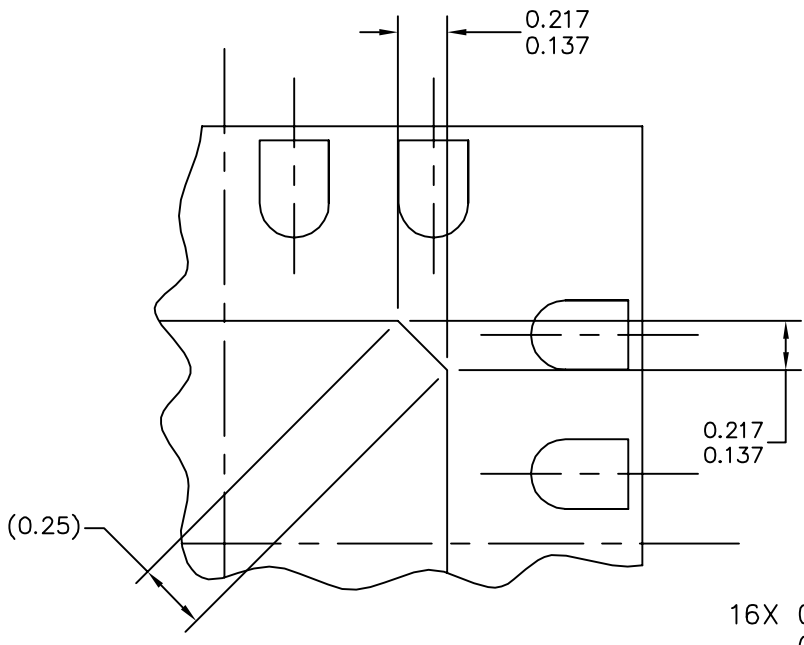
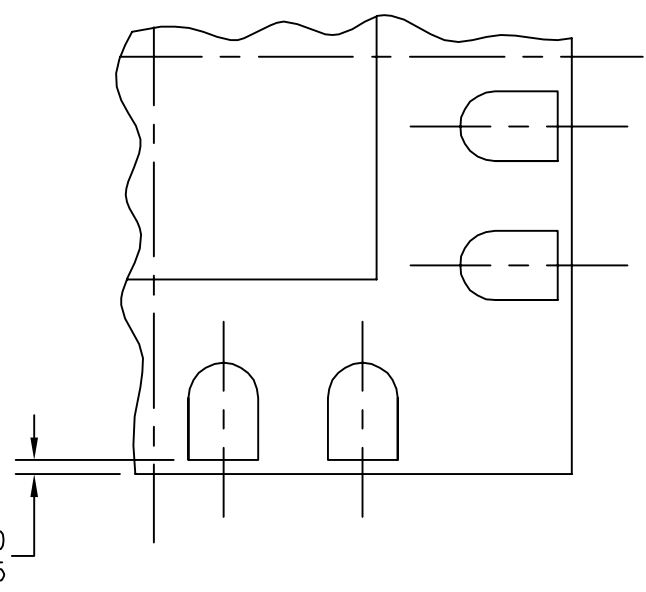


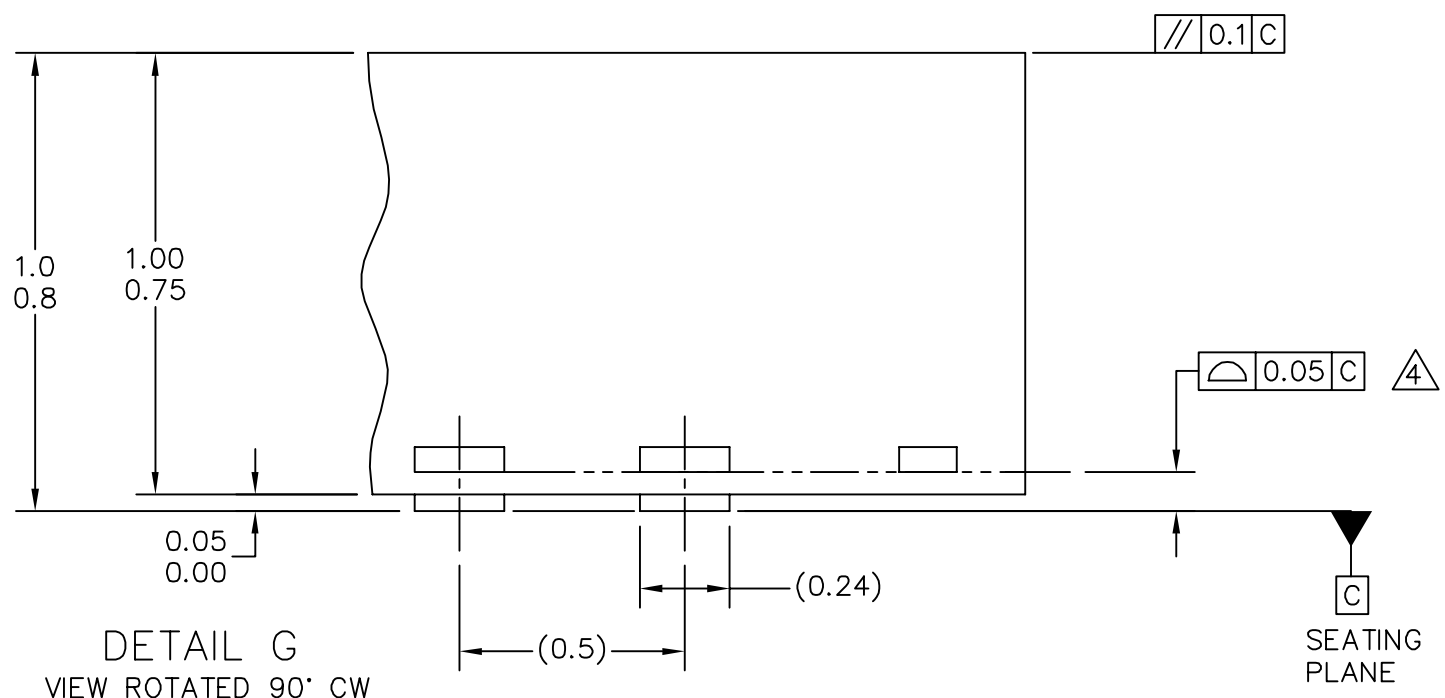
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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 16 TERMINAL, 0.5 PITCH (3 X 3 X 1)	DOCUMENT NO: 98ARL10566D	REV: B	
	CASE NUMBER: 1524-02	28 DEC 2005	
	STANDARD: NON-JEDEC		



DETAIL M
PIN 1 BACKSIDE IDENTIFIER



DETAIL N
CORNER CONFIGURATION




DETAIL G
VIEW ROTATED 90° CW

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TITLE: THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 16 TERMINAL, 0.5 PITCH (3 X 3 X 1)	DOCUMENT NO: 98ARL10566D	REV: B	
	CASE NUMBER: 1524-02	28 DEC 2005	
	STANDARD: NON-JEDEC		



NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFN.
4.  COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP SHOULD BE 0.2MM.

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